Jungjae Park

List of Publications by Year
in descending order

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36	436	11	21
papers	citations	h-index	g-index

840776

713466

36	36	36	149
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	A Review of Thickness Measurements of Thick Transparent Layers Using Optical Interferometry. International Journal of Precision Engineering and Manufacturing, 2019, 20, 463-477.	2.2	62
2	Uncertainty improvement of geometrical thickness and refractive index measurement of a silicon wafer using a femtosecond pulse laser. Optics Express, 2012, 20, 12184.	3.4	55
3	Measurement of thickness profile and refractive index variation of a silicon wafer using the optical comb of a femtosecond pulse laser. Optics Communications, 2013, 305, 170-174.	2.1	39
4	Vibration-insensitive measurements of the thickness profile of large glass panels. Optics Express, 2015, 23, 32941.	3.4	33
5	Vibration-desensitized interferometer by continuous phase shifting with high-speed fringe capturing. Optics Letters, 2010, 35, 19.	3.3	28
6	Fizeau-type interferometric probe to measure geometrical thickness of silicon wafers. Optics Express, 2014, 22, 23427.	3.4	28
7	Modified Roberts-Langenbeck test for measuring thickness and refractive index variation of silicon wafers. Optics Express, 2012, 20, 20078.	3.4	25
8	Total physical thickness measurement of a multi-layered wafer using a spectral-domain interferometer with an optical comb. Optics Express, 2017, 25, 12689.	3.4	23
9	Absolute distance measurement method without a non-measurable range and directional ambiguity based on the spectral-domain interferometer using the optical comb of the femtosecond pulse laser. Applied Physics Letters, 2016, 109, .	3.3	21
10	Physical thickness and group refractive index measurement of individual layers for double-stacked microstructures using spectral-domain interferometry. Optics Communications, 2019, 431, 181-186.	2.1	17
11	Simultaneous measurement method of the physical thickness and group refractive index free from a non-measurable range. Optics Express, 2019, 27, 24682.	3.4	14
12	Sub-100-nm precision distance measurement by means of all-fiber photonic microwave mixing. Optics Express, 2021, 29, 12229.	3.4	13
13	Precise thickness profile measurement insensitive to spatial and temporal temperature gradients on a large glass substrate. Applied Optics, 2020, 59, 5881.	1.8	13
14	Optical method for simultaneous thickness measurements of two layers with a significant thickness difference. Optics Express, 2021, 29, 31615.	3.4	12
15	Optical Fiber-Based Confocal and Interferometric System for Measuring the Depth and Diameter of Through Silicon Vias. Journal of Lightwave Technology, 2016, 34, 5462-5466.	4.6	11
16	A novel method for simultaneous measurement of thickness, refractive index, bow, and warp of a large silicon wafer using a spectral-domain interferometer. Metrologia, 2020, 57, 064001.	1.2	11
17	A Hybrid Non-destructive Measuring Method of Three-dimensional Profile of Through Silicon Vias for Realization of Smart Devices. Scientific Reports, 2018, 8, 15342.	3.3	10
18	Periodic-Error-Free All-Fiber Distance Measurement Method With Photonic Microwave Modulation Toward On-Chip-Based Devices. IEEE Transactions on Instrumentation and Measurement, 2022, 71, 1-7.	4.7	5

#	Article	IF	Citations
19	Active autofocus control using source dithering technique based on fibre-optic confocal principle. International Journal of Precision Engineering and Manufacturing, 2011, 12, 733-736.	2.2	4
20	Precise measurement of the thickness of silicon wafers by double-sided interferometer and bilateral comparison. Metrologia, 2021, 58, 054002.	1.2	4
21	Uncertainty evaluation of the geometrical thickness and refractive index of silicon wafers. Proceedings of SPIE, 2013, , .	0.8	2
22	Simultaneous measurement of the thickness profile and refractive index distribution of silicon wafers. , 2013, , .		2
23	Development of Spectral-Domain Interferometer Having Dual Reference Paths based on Polarization for Measuring Absolute Distances. Journal of the Korean Society for Precision Engineering, 2020, 37, 181-186.	0.2	2
24	A point-diffraction interferometer with vibration-desensitizing capability. , 2006, , .		1
25	Precise thickness measurement and comparison of step-shaped microfluidic channel mold using optical interferometry. , 2019, , .		1
26	Point-diffraction fiber interferometer for vibration desensitization. , 2005, , .		0
27	Continuous scanning phase measurement for high immunity to vibration. Proceedings of SPIE, 2009, , .	0.8	0
28	Dimensional metrology on a semiconductor packaging process using an optical comb. , 2014, , .		0
29	Dimensional metrology for smart devices using the optical comb of femtosecond pulse lasers. , 2015, , .		0
30	Physical thickness and group refractive index measurement of bare glass panels using the optical comb for display industry. , 2015, , .		0
31	Performance evaluation on the diameter and depth measurements of through-silicon vias using a spectral-domain interferometer. , 2016, , .		0
32	Thickness profile measurement of the double-layered glass substrate based on transmission-type spectral domain interferometer. , 2016, , .		0
33	3D profile measurement of small patterns for semiconductor devices using an optical fiber-based interferometric system integrated with confocal microscopy. , 2017, , .		0
34	Development of a High-Speed Depth Measuring Machine for through Silicon Vias on a 300 mm Silicon Wafer. Journal of the Korean Society for Precision Engineering, 2017, 34, 311-314.	0.2	0
35	Analysis of measurement error caused by swing motion for determining the physical thickness and group refractive index of a large glass panel. , 2019, , .		0
36	Recent Trends on a Precision Dimensional Sensor Using Optical Modulation Techniques. Journal of the Korean Society for Precision Engineering, 2021, 38, 889-896.	0.2	0